

## REVERSE WIRE BONDING TECHNIQUES

### ABSTRACT OF THE DISCLOSURE

- 5           Thin molded semiconductor device packages that contain two semiconductor dice  
and techniques for forming such packages are described. The packages and techniques  
mainly involve reverse wirebonding the bonding wires that connect the dice to  
surrounding conductive contact leads. Techniques for ball bonding a first end of a  
bonding wire to a contact lead and a second end of the bonding wire to a semiconductor  
10 die are described. Techniques for stitch bonding a bonding wire to both a contact lead  
and a semiconductor die is also described.

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